

Bringing tomorrow's electronics to life



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MRSI Systems (Mycronic Group), is the leading manufacturer of fully automated, high-speed, high-precision and flexible eutectic and epoxy die bonding systems. We offer solutions for research and development, low-to-medium volume production, and high-volume manufacturing of photonic devices such as lasers, detectors, modulators, AOCs, WDM/EML TO-Cans, Optical transceivers, LiDAR, VR/AR, sensors, and optical imaging products. With 40+ years of industry experience and our worldwide local technical support team, we provide the most effective systems and assembly solutions for all packaging levels including chip-on-wafer (CoW), chip-on-carrier (CoC), PCB, and gold-box packaging. For more information visit www.mrsisystems.com.

Mycronic is a Swedish high-tech company engaged in the development, manufacture and marketing of production equipment with high precision and flexibility requirements for the electronics industry. Mycronic headquarters is located in Täby, north of Stockholm and the Group has subsidiaries in China, France, Germany, Japan, Singapore, South Korea, the Netherlands, United Kingdom and the United States. Mycronic (MYCR) is listed at Nasdaq Stockholm. www.mycronic.com


Specifications are subject to change without notice.

202409_MRSI-175AGV1

MRSI-175Ag EPOXY DISPENSER

**NEXT
GENERATION**





MRSI Systems has been serving optoelectronic and microelectronic customers for over 40 years and understands their requirement to scale efficiently in today's fast-paced marketplace.

Applications exist across a wide range of market segments, such as life & health sciences, aerospace, defense, automotive, lighting, communications, and more.

MRSI's die bonding solutions help our customers to enable just-in-time supply and fast-pace innovations of critical components for high-growth market segments. The MRSI-175Ag Conductive Epoxy Dispenser handles the most demanding dispensing applications such as semiconductor packaging, microwave & RF modules, multi-chip modules, optical modules, hybrid circuits, sensors, and MEMS.

Our die bonding solutions are built on standardized hardware and software platforms configured to minimize process deviations, reduce NPI cost, deliver long term proven product reliability and supported by our global customer service team. These factors deliver the best financial returns in the industry.



MRSI-175Ag Next Generation Epoxy Dispenser Highly Configurable



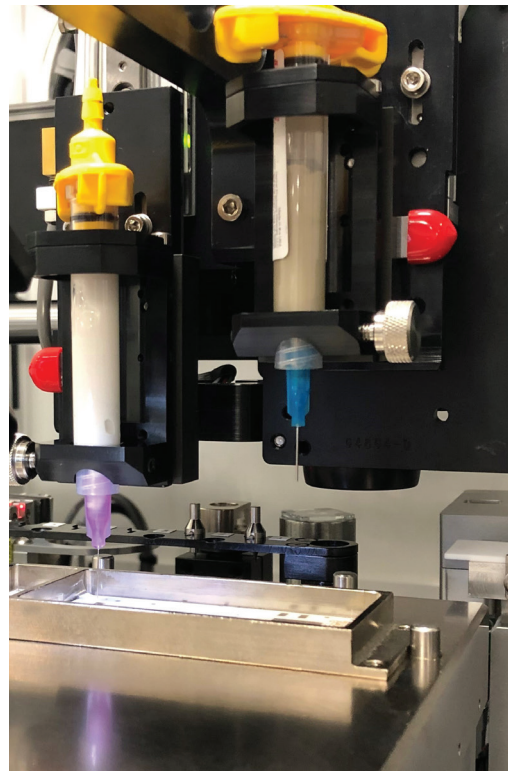
Assembly Technologies

- Underfill
- Epoxy die attach
- Encapsulation
- Multi-pin stamping
- UV epoxy



Flexible Dispensing Platform

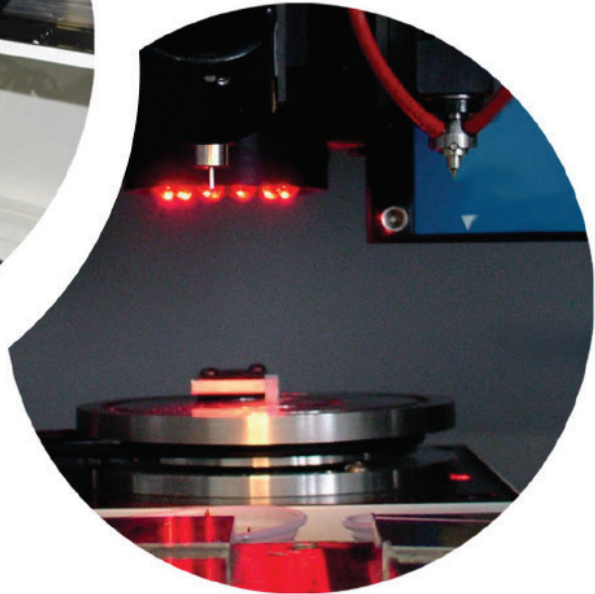
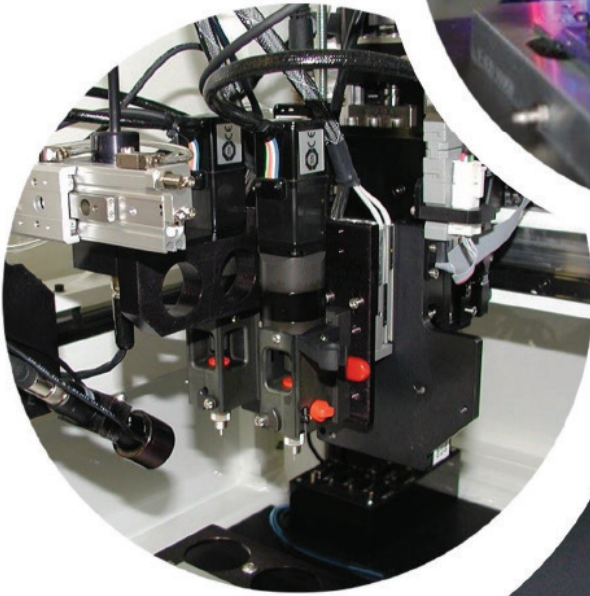
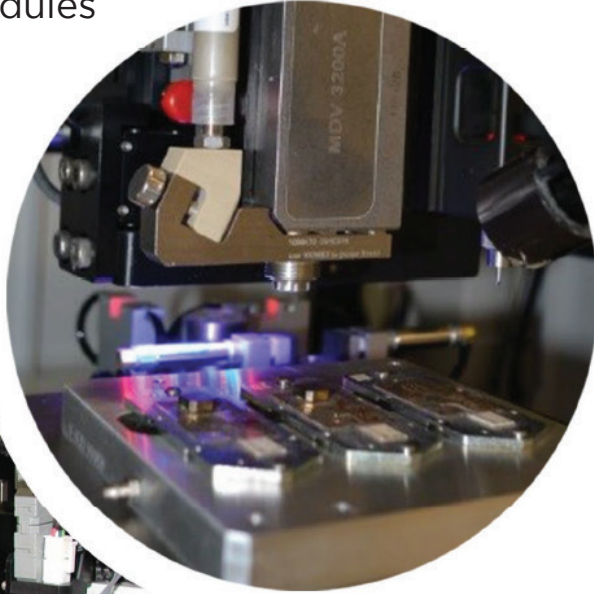
- Increased capacity at lower cost
- Lower cost of ownership
- Less labor cost
- Higher yields
- Flexibility
- Ultra-high speed
- 35% more energy efficient
- 25 μ m accuracy (10 μ m accuracy MRSI-175Ag+ available)





Applications

- Semiconductor packaging
- Microwave & RF modules
- Multi-chip modules
- Optical modules
- Hybrid circuits
- Sensors
- MEMS



Options

- Laser height sensor
- Confocal height sensor
- Conveyor
- Jet
- Stamping
- Real-time video monitoring